



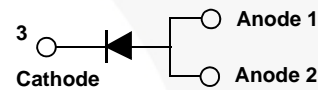
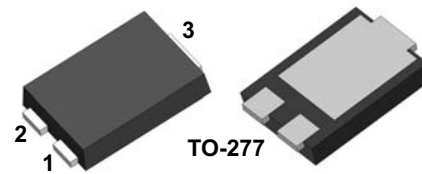
July 2015

# FSV10150V

## 10 A, 150 V Ultra-Low VF Schottky Rectifier

### Features

- Ultra-Low Forward Voltage Drop
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- Trench Schottky Technology
- RoHS Compliant
- Green Molding Compound as per IEC61249 Standard
- Lead Free in Compliance with EU RoHS 2011/65/EU Directive
- Qualified per AEC-Q101 Rev. C Standard



### Ordering Information

Part Number	Top Mark	Package	Packing Method
FSV10150V	FSV10150V	TO-277 3L	Tape and Reel

### Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage	150	V
$V_{RWM}$	Working Peak Reverse Voltage	150	V
$V_{RMS}$	RMS Reverse Voltage	106	V
$V_R$	DC Blocking Voltage	150	V
$I_{F(AV)}$	Average Rectified Peak Forward Surge Current	10	A
$I_{FSM}$	Non-Repetitive Peak Forward Surge Current	180	A
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

FSV10150V — 10 A, 150 V Ultra-Low VF Schottky Rectifier

### Thermal Characteristics<sup>(1)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	100	40	$^\circ\text{C}/\text{W}$
$\Psi_{JL}$	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	$^\circ\text{C}/\text{W}$
	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	

**Note:**

- The thermal resistances ( $R_{\theta JA}$  &  $\Psi_{JL}$ ) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



Figure 1. Minimum Land Pattern of 2 oz Copper

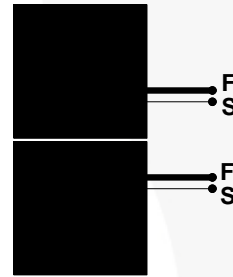


Figure 2. Maximum Land Pattern of 2 oz Copper

### Electrical Characteristics

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_R$	Breakdown Voltage	$I_R = 0.5 \text{ mA}$	150			V
$V_F$	Forward Voltage Drop	$I_F = 10 \text{ A}$			0.84	V
$I_R$	Reverse Current	$V_R = 150 \text{ V}$			20	$\mu\text{A}$

### Typical Performance Characteristics

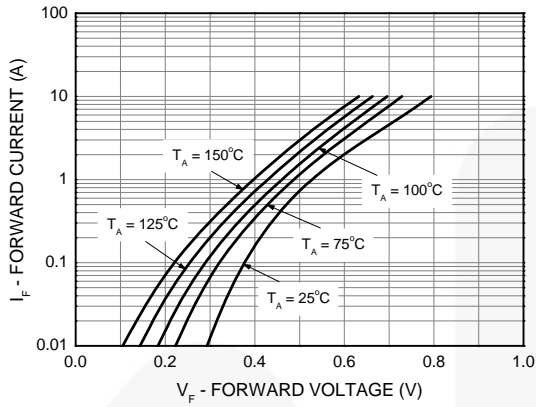


Figure 3. Typical Forward Characteristics

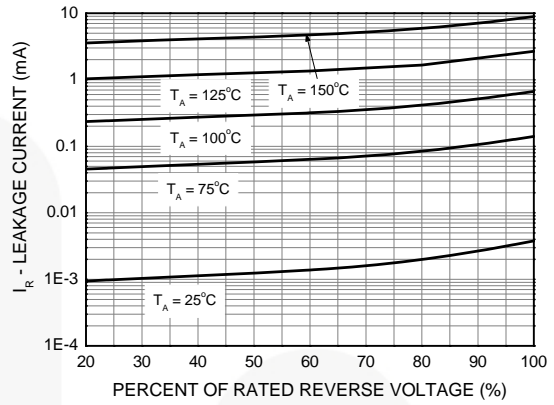


Figure 4. Typical Reverse Characteristics

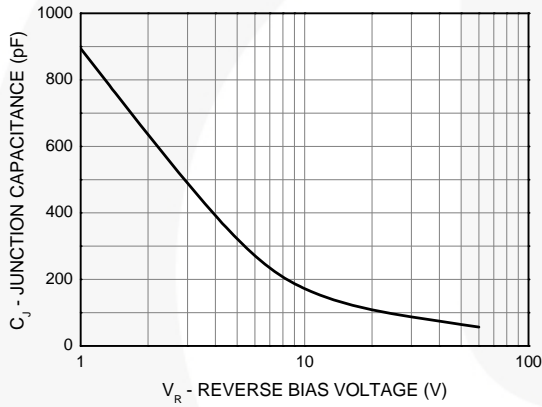


Figure 5. Typical Junction Capacitance

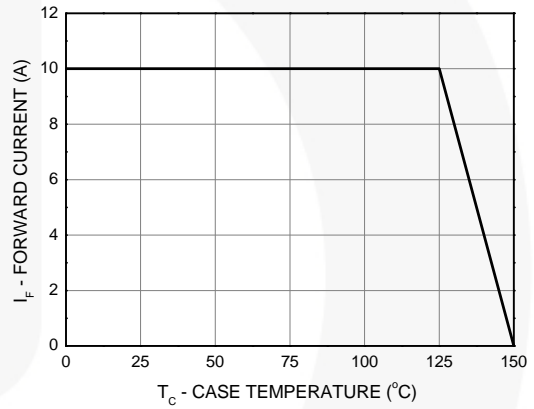
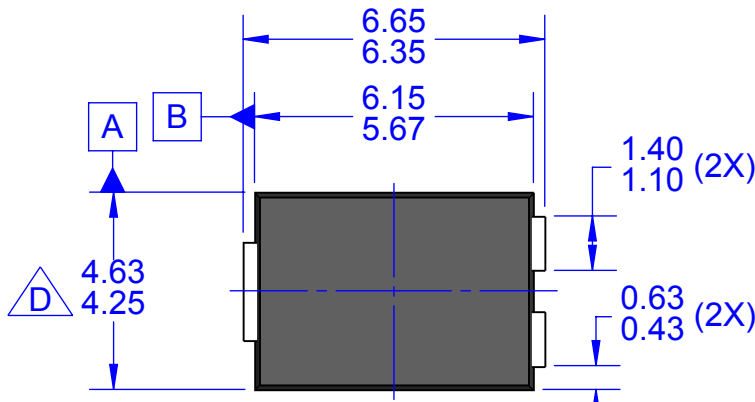
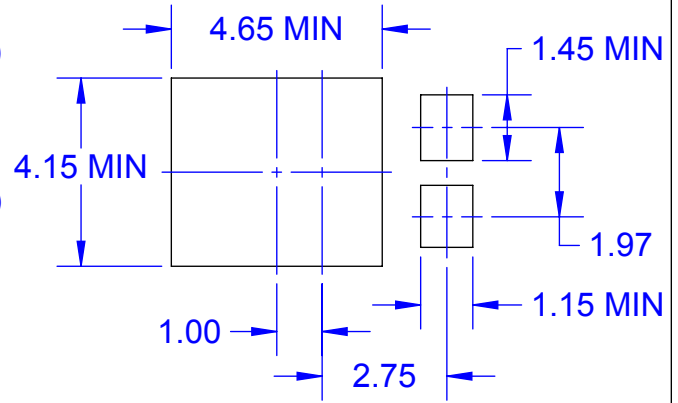


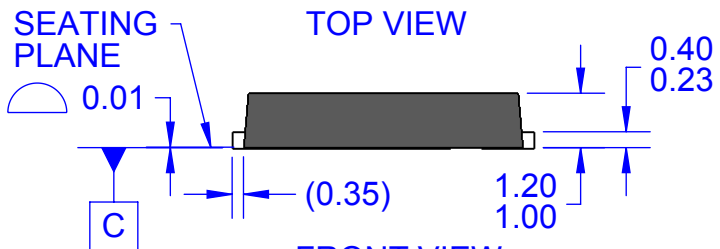
Figure 6. Forward Current Derating Curve



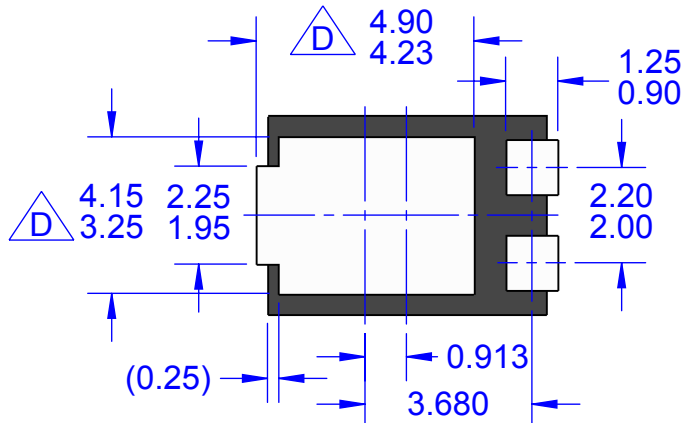
TOP VIEW



LAND PATTERN RECOMMENDATION



FRONT VIEW

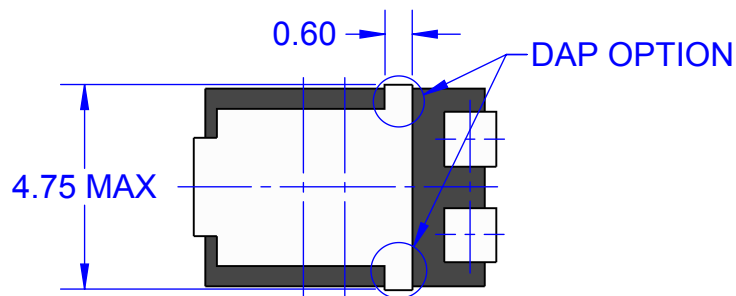


BOTTOM VIEW

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- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.

- $\triangle$  D DOES NOT COMPLY TO JEDEC STANDARD VALUE.
- E. DRAWING FILENAME: MKT-TO277A03rev5



BOTTOM VIEW - DAP OPTION





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